



Material Content Data Sheet



Sales Product Name				ESD0P4RFL E6327		Issued		25. January 2018	
MA#				MA001714658					
Package				PG-TSLP-4-7		Weight*		0.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.09		897		
	noble metal	gold	7440-57-5	0.003	0.35		3477		
	inorganic material	silicon	7440-21-3	0.041	4.24	4.68	42431	46805	
leadframe	non noble metal	nickel	7440-02-0	0.265	27.58	27.58	275840	275840	
wire	noble metal	gold	7440-57-5	0.008	0.85	0.85	8460	8460	
	encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		313	
	organic material	carbon black	1333-86-4	0.006	0.63		6268		
	plastics	epoxy resin	-	0.081	8.46		84610		
	inorganic material	silicondioxide	60676-86-0	0.515	53.55	62.67	535549	626740	
leadfinish	noble metal	gold	7440-57-5	0.014	1.41	1.41	14052	14052	
plating	noble metal	gold	7440-57-5	0.027	2.81	2.81	28103	28103	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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